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November 2013

### **FQP27N25**

# N-Channel QFET<sup>®</sup> MOSFET 250 V, 25.5 A, 110 m $\Omega$

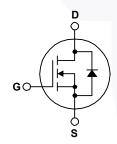
### Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

### **Features**

- 25.5 A, 250 V,  $R_{DS(on)}$  = 110 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 12.75 A
- Low Gate Charge (Typ. 50 nC)
- · Low Crss (Typ. 45 pF)
- · 100% Avalanche Tested





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

| Symbol                            | Parameter  |          | FQP27N25    | Unit |
|-----------------------------------|--|----------|-------------|------|
| $V_{DSS}$                         | Drain-Source Voltage   |          | 250         | V    |
| I <sub>D</sub>                    | Drain Current - Continuous (T <sub>C</sub> = 25°C)                   | )        | 25.5        | А    |
|                                   | - Continuous (T <sub>C</sub> = 100°C                                 | C)       | 16.2        | Α    |
| I <sub>DM</sub>                   | Drain Current - Pulsed   | (Note 1) | 102         | A    |
| V <sub>GSS</sub>                  | Gate-Source Voltage  |          | ± 30        | V    |
| E <sub>AS</sub>                   | Single Pulsed Avalanche Energy                                       | (Note 2) | 600         | mJ   |
| I <sub>AR</sub>                   | Avalanche Current  | (Note 1) | 25.5        | A    |
| E <sub>AR</sub>                   | Repetitive Avalanche Energy  | (Note 1) | 18          | mJ   |
| dv/dt                             | Peak Diode Recovery dv/dt  | (Note 3) | 5.5         | V/ns |
| P <sub>D</sub>                    | Power Dissipation (T <sub>C</sub> = 25°C)                            |          | 180         | W    |
|                                   | - Derate above 25°C  |          | 1.43        | W/°C |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Temperature Range                              |          | -55 to +150 | °C   |
| T <sub>L</sub>                    | Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds |          | 300         | °C   |

### **Thermal Characteristics**

| Symbol          | Parameter                                     | FQP27N25 | Unit |
|-----------------|---|----------|------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Max.    | 0.7      | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 62.5     | °C/W |

### **Package Marking and Ordering Information**

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-------------|----------|---------|----------------|-----------|------------|----------|
| FQP27N25    | FQP27N25 | TO-220  | Tube           | N/A       | N/A        | 50 units |

### **Electrical Characteristics**

T<sub>C</sub> = 25°C unless otherwise noted.

| Symbol   | Parameter  | Test Conditions  | Min          | Тур   | Max                                  | Uni            |
|--|--|--|--------------|---|--------------------------------------|----------------|
| Off Cha  | aracteristics  |  |              |   |                                      |                |
| BV <sub>DSS</sub>  | Drain-Source Breakdown Voltage   | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$  | 250          |   |                                      | V              |
| ΔBV <sub>DSS</sub><br>/ ΔT <sub>J</sub>  | Breakdown Voltage Temperature<br>Coefficient   | I <sub>D</sub> = 250 μA, Referenced to 25°C  |              | 0.29  |                                      | V/°(           |
| I <sub>DSS</sub>   | Zero Gate Voltage Drain Current  | V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V   |              |   | 1                                    | μΑ             |
|  | Zero Gate Voltage Drain Current  | V <sub>DS</sub> = 200 V, T <sub>C</sub> = 125°C  |              |   | 10                                   | μA             |
| I <sub>GSSF</sub>  | Gate-Body Leakage Current, Forward   | V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V  |              |   | 100                                  | n/             |
| I <sub>GSSR</sub>  | Gate-Body Leakage Current, Reverse   | V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V   |              |   | -100                                 | nA             |
| On Cha   | aracteristics  |  |              |   |                                      |                |
| V <sub>GS(th)</sub>  | Gate Threshold Voltage   | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$   | 3.0          |   | 5.0                                  | V              |
| R <sub>DS(on)</sub>  | Static Drain-Source<br>On-Resistance   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12.75 A   |              | 0.083                                       | 0.11                                 | Ω              |
| 0  | Forward Transconductance   | V <sub>DS</sub> = 50 V, I <sub>D</sub> = 12.75 A   |              | 24  |                                      | S              |
| 9FS  | 1 orward framedoridation   | B0 · B   |              |   |                                      | U              |
| Dynam  | ic Characteristics   |  |              |   |                                      |                |
| <b>Dynam</b><br>C <sub>iss</sub>   |  | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,   |              | 1900  | 2450                                 |                |
| <b>Dynam</b><br>C <sub>iss</sub><br>C <sub>oss</sub>   | ic Characteristics   | 30 3   |              |   | 2450<br>470                          | pF             |
| 9FS  Dynam  C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>   | ic Characteristics Input Capacitance   | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,   |              | 1900  |                                      | pF<br>pF       |
| Dynam C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>   | ic Characteristics Input Capacitance Output Capacitance  | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,   |              | 1900<br>360                                 | 470                                  | pF<br>pF       |
| Dynam C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>   | ic Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance   | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,<br>f = 1.0 MHz  |              | 1900<br>360                                 | 470                                  | pF<br>pF       |
| Dynam C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub> Switch  | ic Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance ing Characteristics   | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, I_{D} = 27 \text{ A},$                     |              | 1900<br>360<br>45                           | 470<br>60                            | pF<br>pF<br>pF |
| Dynam C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub> Switch  | ic Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance ing Characteristics Turn-On Delay Time  | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, I_{D} = 27 \text{ A},$ $R_{G} = 25 \Omega$ |              | 1900<br>360<br>45                           | 470<br>60<br>75                      | pF<br>pF<br>pF |
| Dynam C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub> Switch t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub>                                | ic Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance ing Characteristics Turn-On Delay Time Turn-On Rise Time  | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, I_{D} = 27 \text{ A},$                     |              | 1900<br>360<br>45<br>32<br>270              | 470<br>60<br>75<br>550               | pF<br>pF<br>pF |
| $\begin{array}{c} \textbf{Dynam} \\ C_{iss} \\ C_{oss} \\ C_{rss} \\ \textbf{Switch} \\ \\ ^{t_{d(on)}} \\ t_{r} \\ \\ ^{t_{d(off)}} \\ \end{array}$ | ic Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time                    | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$ $V_{DD} = 125 \text{ V}, I_{D} = 27 \text{ A},$ $R_{G} = 25 \Omega$ | <br><br>     | 1900<br>360<br>45<br>32<br>270<br>80        | 470<br>60<br>75<br>550<br>170        | pF<br>pF<br>pF |
| Dynam C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>   | ic Characteristics Input Capacitance Output Capacitance Reverse Transfer Capacitance ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz $V_{DD} = 125 \text{ V}, I_D = 27 \text{ A},$ $R_G = 25 \Omega$ (Note 4)      | <br><br><br> | 1900<br>360<br>45<br>32<br>270<br>80<br>120 | 470<br>60<br>75<br>550<br>170<br>250 | pF<br>pF       |

### **Drain-Source Diode Characteristics and Maximum Ratings**

| I <sub>S</sub>  | Maximum Continuous Drain-Source Diode Forward Current |  |  |     | 25.5 | Α  |
|-----------------|---|--|--|-----|------|----|
| I <sub>SM</sub> | Maximum Pulsed Drain-Source Diode Forward Current     |  |  |     | 102  | Α  |
| V <sub>SD</sub> | Drain-Source Diode Forward Voltage                    | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 25.5 A |  |     | 1.5  | V  |
| t <sub>rr</sub> | Reverse Recovery Time                                 | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 27 A,  |  | 220 |      | ns |
| Q <sub>rr</sub> | Reverse Recovery Charge                               | dI <sub>F</sub> / dt = 100 A/μs                |  | 1.8 |      | μC |

- **Notes:** 1. Repetitive Rating : Pulse width limited by maximum junction temperature. 2. L = 1.5 mH, I $_{AS}$  = 25.5 A, V $_{DD}$  = 50 V, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C. 3. I $_{SD}$   $\leq$  27 A, di/dt  $\leq$  300 A $\mu$ I $_{IS}$ , V $_{DD}$   $\leq$  BV $_{DSS}$ , starting T $_{J}$  = 25°C. 4. Essentially independent of operating temperature.

### **Typical Characteristics**

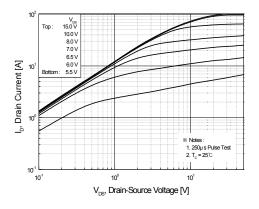
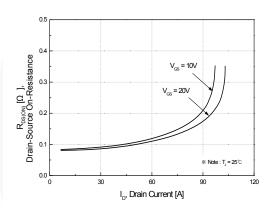


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



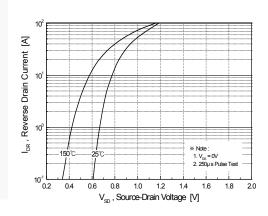
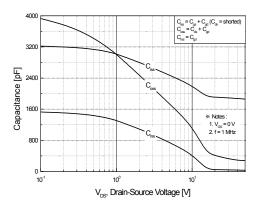


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



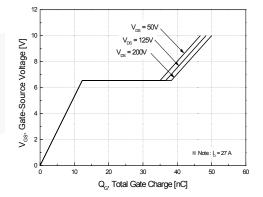
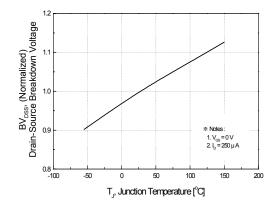


Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

### Typical Characteristics (continued)



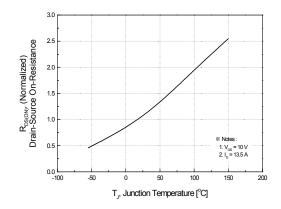
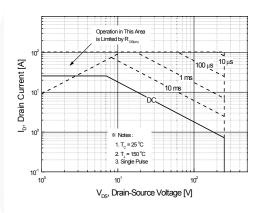


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



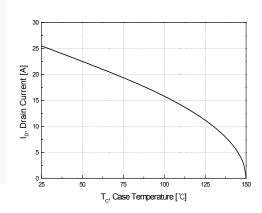


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

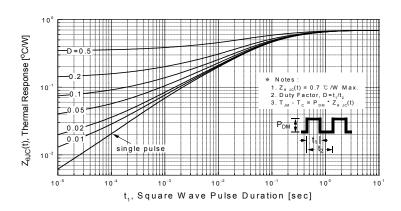


Figure 11. Transient Thermal Response Curve

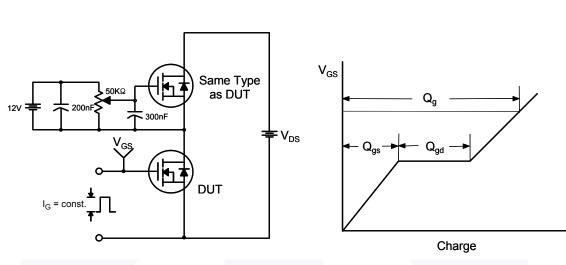


Figure 12. Gate Charge Test Circuit & Waveform

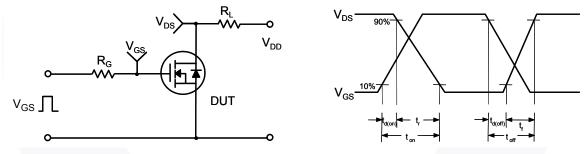


Figure 13. Resistive Switching Test Circuit & Waveforms

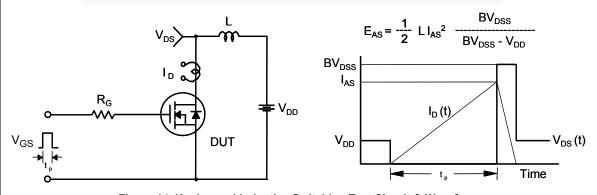
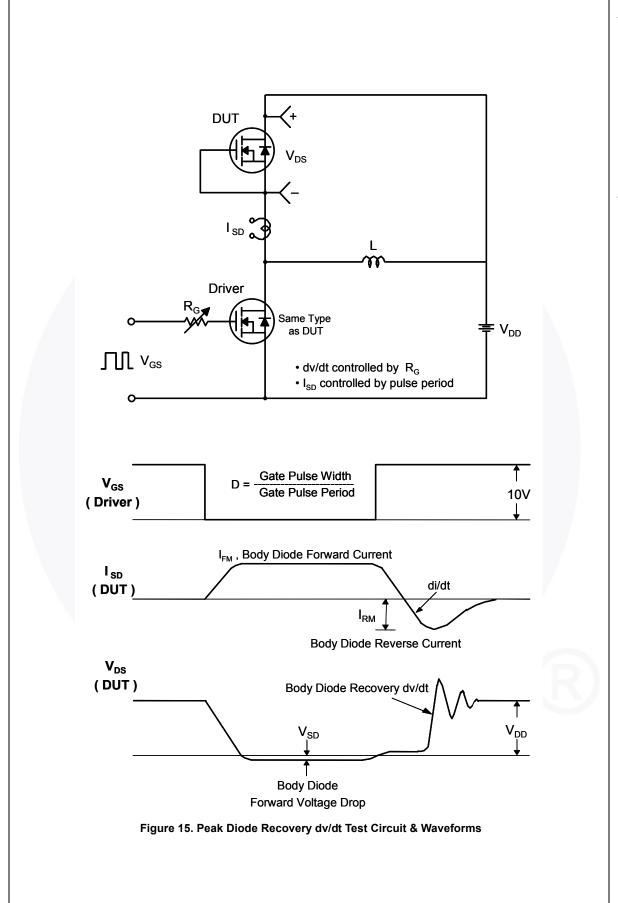
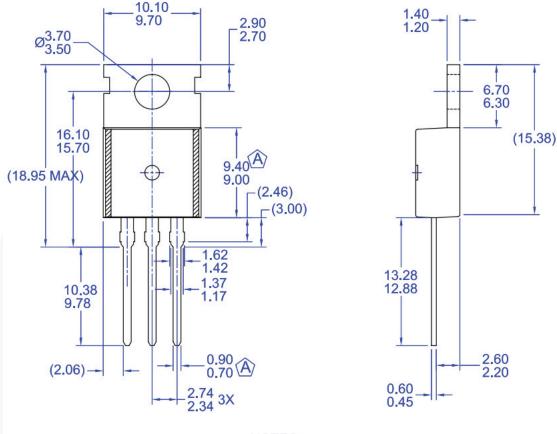


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



### **Mechanical Dimensions**



4.70 10.20 9.80

### NOTES:

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Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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